

## APPLICATION

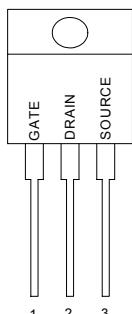
- ◆ DC motor control
- ◆ UPS
- ◆ Class D Amplifier

V <sub>DSS</sub>	R <sub>DS(ON)</sub> Typ.	I <sub>D</sub>
60V	15.8mΩ	60A

## PIN CONFIGURATION

TO-220  
Front View

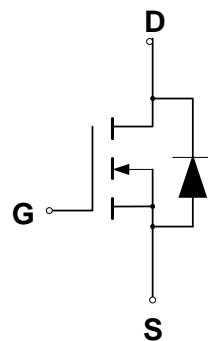
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## FEATURES

- ◆ Low ON Resistance
- ◆ Low Gate Charge
- ◆ Peak Current vs Pulse Width Curve
- ◆ Inductive Switching Curves

## SYMBOL



N-Channel MOSFET

## ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain to Source Voltage (Note 1)	V <sub>DSS</sub>	60	V
Drain to Current - Continuous T <sub>c</sub> = 25 , V <sub>GS</sub> @10V	I <sub>D</sub>	60	A
- Continuous T <sub>c</sub> = 100 , V <sub>GS</sub> @10V	I <sub>D</sub>	43	
- Pulsed T <sub>c</sub> = 25 , V <sub>GS</sub> @10V (Note 2)	I <sub>DM</sub>	241	
Gate-to-Source Voltage - Continue	V <sub>GS</sub>	±20	V
Total Power Dissipation	P <sub>D</sub>	150	W
Derating Factor above 25		1.0	W/
Peak Diode Recovery dv/dt (Note 3)	dv/dt	4.5	V/ns
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to 175	
Single Pulse Avalanche Energy L=144μH,I <sub>D</sub> =40 Amps	E <sub>AS</sub>	500	mJ
Maximum Lead Temperature for Soldering Purposes	T <sub>L</sub>	300	
Maximum Package Body for 10 seconds	T <sub>PKG</sub>	260	
Pulsed Avalanche Rating	I <sub>AS</sub>	60	A

## THERMAL RESISTANCE

Symbol	Parameter	Min	Typ	Max	Units	Test Conditions
R <sub>θJC</sub>	Junction-to-case			1.0	/W	Water cooled heatsink, P <sub>D</sub> adjusted for a peak junction temperature of +175
R <sub>θJA</sub>	Junction-to-ambient			62	/W	1 cubic foot chamber, free air



CMT60N06

N-CHANNEL Logic Level Power MOSFET

## ORDERING INFORMATION

Part Number	Package
CMT60N06	TO-220

## ELECTRICAL CHARACTERISTICS

Unless otherwise specified,  $T_J = 25^\circ C$ .

Characteristic		CMT60N06			
OFF Characteristics		Symbol	Min	Typ	Max
Drain-to-Source Breakdown Voltage ( $V_{GS} = 0 V$ , $I_D = 250 \mu A$ )	$V_{DSS}$	60			V
Breakdown Voltage Temperature Coefficient (Reference to 25°C, $I_D = 250 \mu A$ )	$V_{DSS}/\Delta T_J$		0.069		mV/°C
Drain-to-Source Leakage Current ( $V_{DS} = 60 V$ , $V_{GS} = 0 V$ , $T_J = 25^\circ C$ ) ( $V_{DS} = 48 V$ , $V_{GS} = 0 V$ , $T_J = 150^\circ C$ )	$I_{DS(on)}$			25 250	$\mu A$
Gate-to-Source Forward Leakage ( $V_{GS} = 20 V$ )	$I_{GSS}$			100	nA
Gate-to-Source Reverse Leakage ( $V_{GS} = -20 V$ )	$I_{GRR}$			-100	nA
ON Characteristics					
Gate Threshold Voltage ( $V_{DS} = V_{GS}$ , $I_D = 250 \mu A$ )	$V_{GS(th)}$	1.0	2.0	3.0	V
Static Drain-to-Source On-Resistance (Note 4) ( $V_{GS} = 10 V$ , $I_D = 60 A$ )	$R_{DS(on)}$		15.8	18	$m\Omega$
Forward Transconductance ( $V_{DS} = 15 V$ , $I_D = 60 A$ ) (Note 4)	$g_{FS}$		36		S
Dynamic Characteristics					
Input Capacitance	$(V_{DS} = 25 V, V_{GS} = 0 V, f = 1.0 \text{ MHz})$	$C_{iss}$	1430		pF
Output Capacitance		$C_{oss}$	420		pF
Reverse Transfer Capacitance		$C_{rss}$	88		pF
Total Gate Charge ( $V_{GS} = 10 V$ )	$(V_{DS} = 30 V, I_D = 60 A, V_{GS} = 10 V)$ (Note 5)	$Q_g$	37.7		nC
Gate-to-Source Charge		$Q_{gs}$	8.4		nC
Gate-to-Drain ("Miller") Charge		$Q_{gd}$	9.8		nC
Resistive Switching Characteristics					
Turn-On Delay Time	$(V_{DD} = 30 V, I_D = 60 A, V_{GS} = 10 V, R_G = 9.1 \Omega)$ (Note 5)	$t_{d(on)}$	12.1		ns
Rise Time		$t_{rise}$	64		ns
Turn-Off Delay Time		$t_{d(off)}$	69		ns
Fall Time		$t_{fall}$	39		ns
Source-Drain Diode Characteristics					
Continuous Source Current (Body Diode)	Integral pn-diode in MOSFET	$I_S$		60	A
Pulse Source Current (Body Diode)		$I_{SM}$		241	A
Diode Forward On-Voltage	$(I_S = 60 A, V_{GS} = 0 V)$	$V_{SD}$		1.5	V
Reverse Recovery Time	$(I_F = 60 A, V_{GS} = 0 V, dI/dt = 100 A/\mu s)$	$t_{rr}$	55		ns
Reverse Recovery Charge		$Q_{rr}$	110		nC



**CMT60N06**

**N-CHANNEL Logic Level Power MOSFET**

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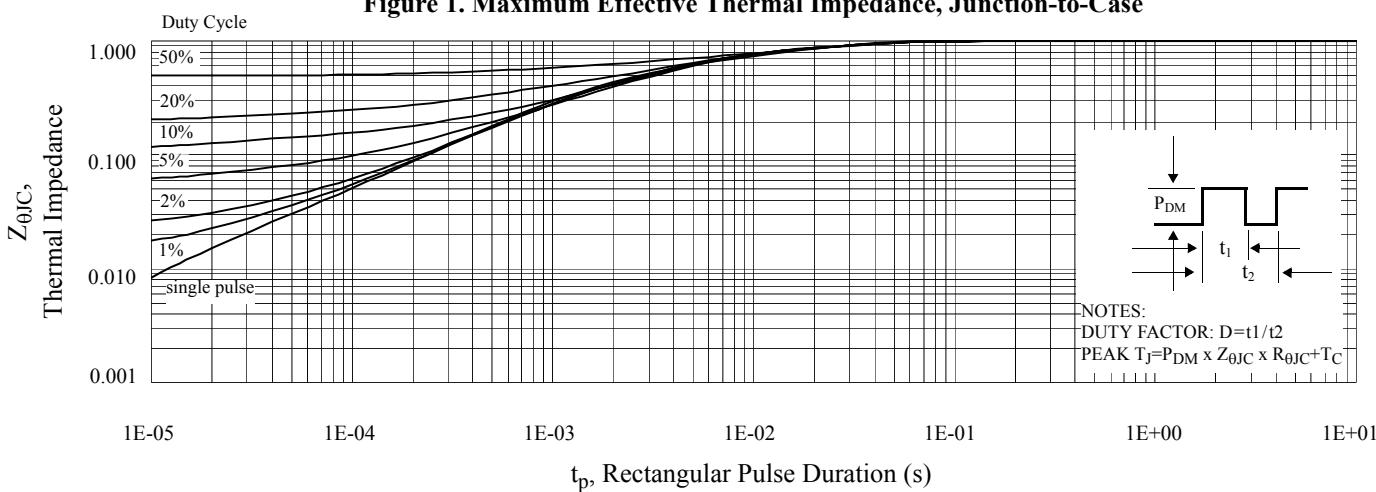
Note 1:  $T_J = +25$  to  $+175$

Note 2: Repetitive rating; pulse width limited by maximum junction temperature.

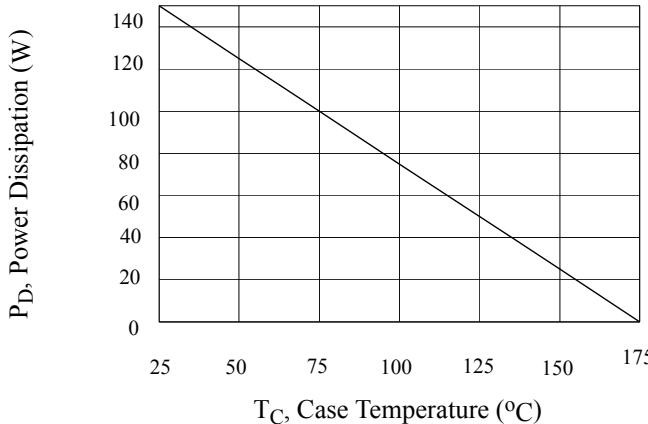
Note 3:  $I_{SD} = 60A$ ,  $dI/dt \leq 100A/\mu s$ ,  $V_{DD} \leq BV_{DSS}$ ,  $T_J = +175$

Note 4: Pulse width  $\leq 250\mu s$ ; duty cycle  $\leq 2\%$

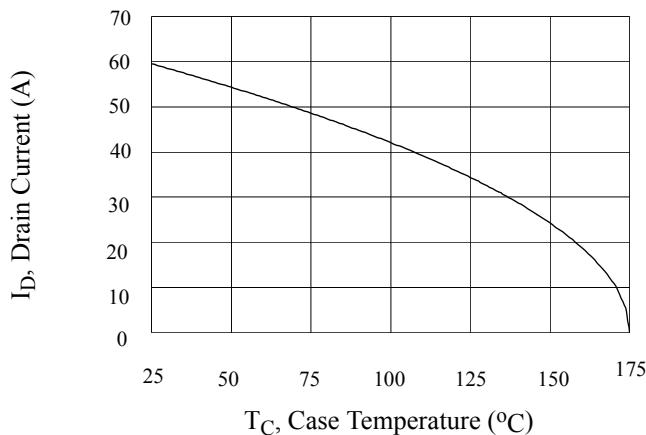
Note 5: Essentially independent of operating temerpature.



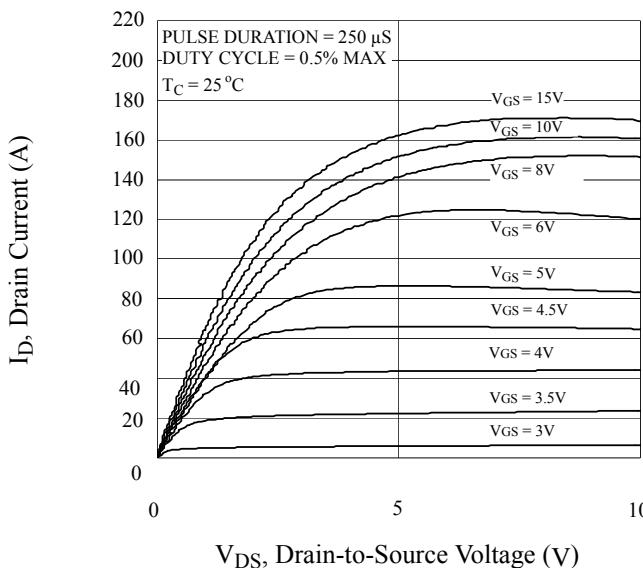
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**Figure 2. Maximum Power Dissipation vs Case Temperature**



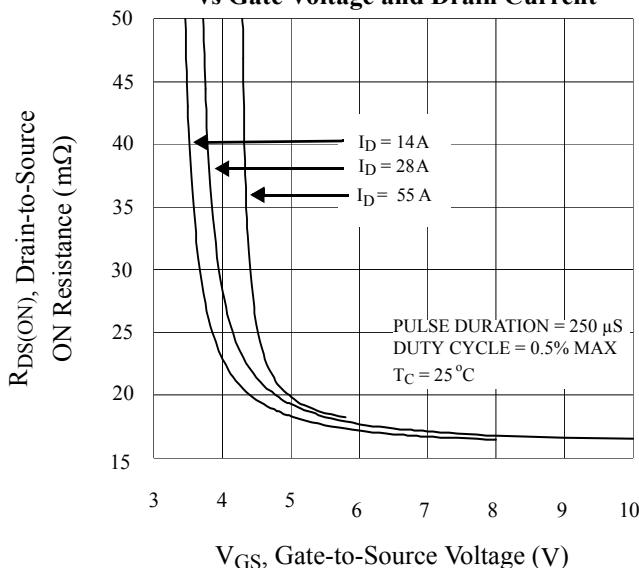
**Figure 3. Maximum Continuous Drain Current vs Case Temperature**



**Figure 4. Typical Output Characteristics**



**Figure 5. Typical Drain-to-Source ON Resistance vs Gate Voltage and Drain Current**



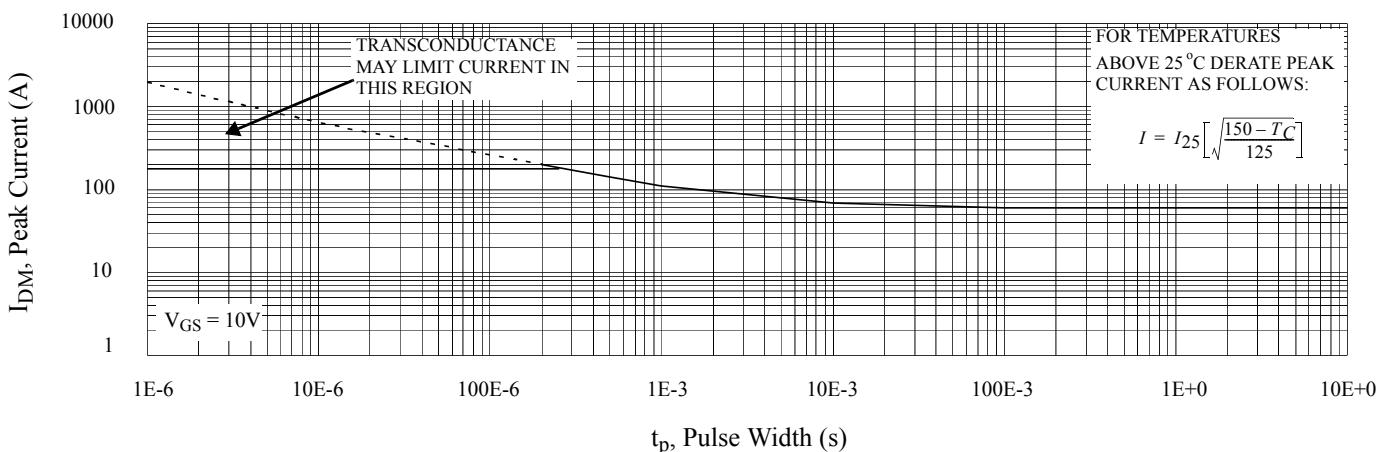
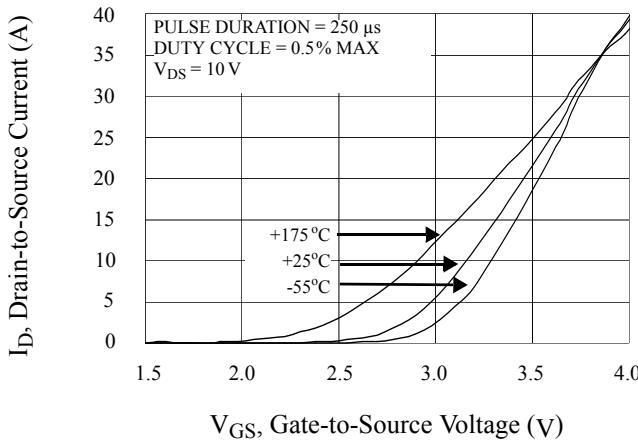
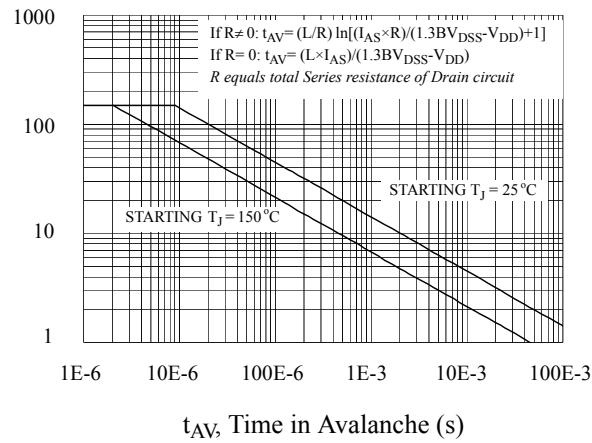
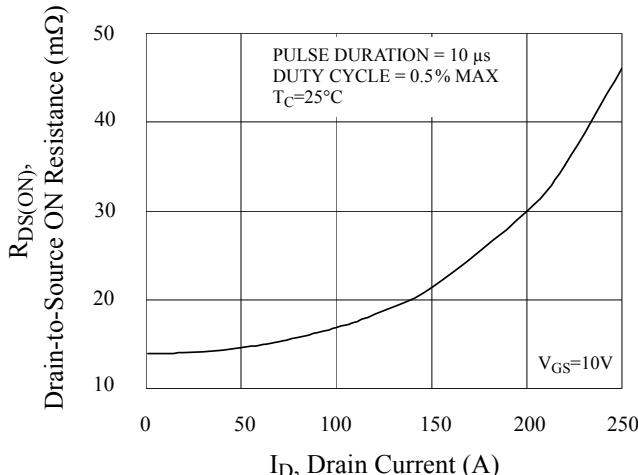
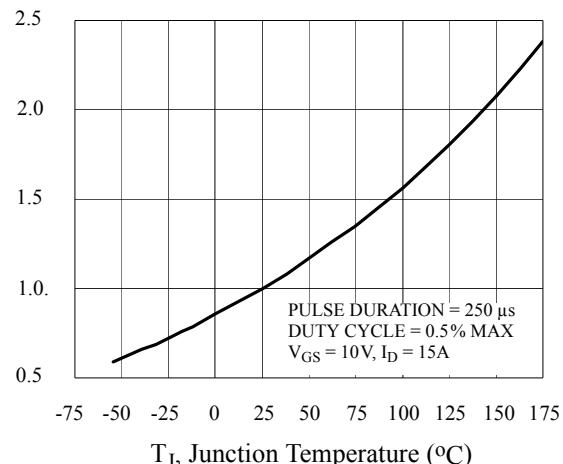
**Figure 6. Maximum Peak Current Capability**

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**Figure 7. Typical Transfer Characteristics**

**Figure 8. Unclamped Inductive Switching Capability**

**Figure 9. Typical Drain-to-Source ON Resistance vs Drain Current**

**Figure 10. Typical Drain-to-Source ON Resistance vs Junction Temperature**


Figure 11. Typical Breakdown Voltage vs Junction Temperature

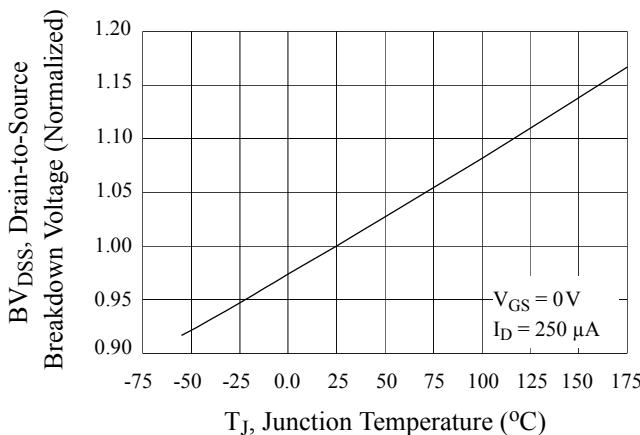
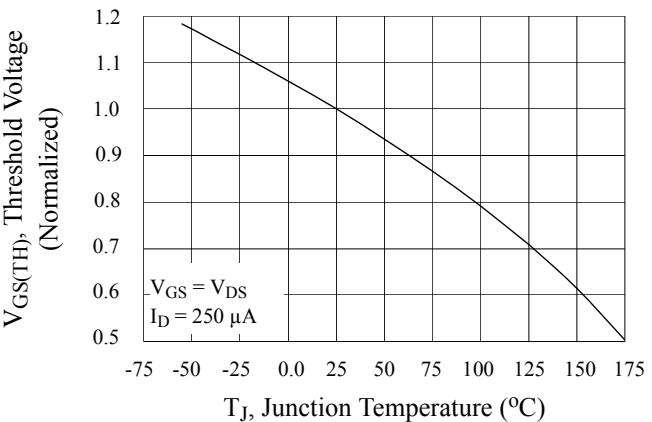


Figure 12. Typical Threshold Voltage vs Junction Temperature



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Figure 13. Maximum Forward Bias Safe Operating Area

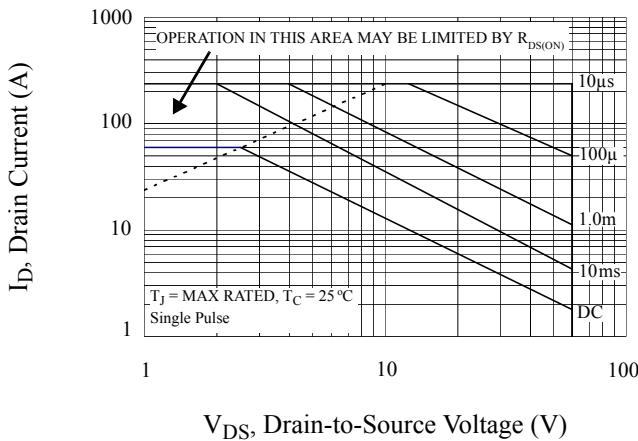


Figure 14. Typical Capacitance vs Drain-to-Source Voltage

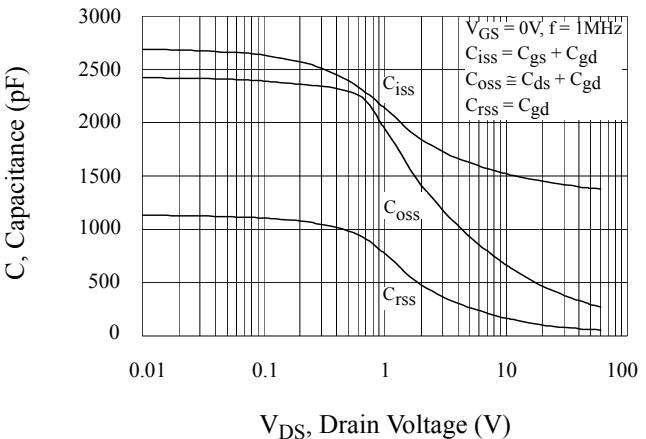
V<sub>GS</sub>, Gate-to-Source Voltage (V)

Figure 15. Typical Gate Charge vs Gate-to-Source Voltage

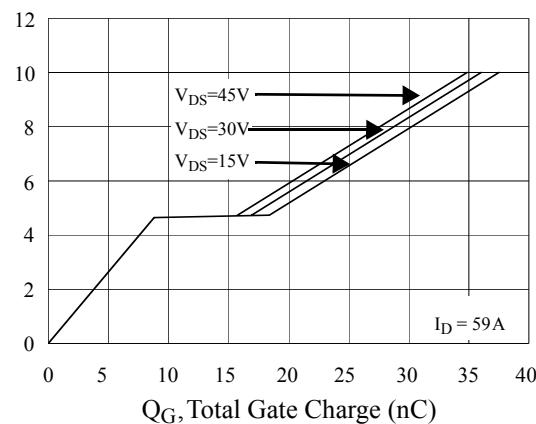
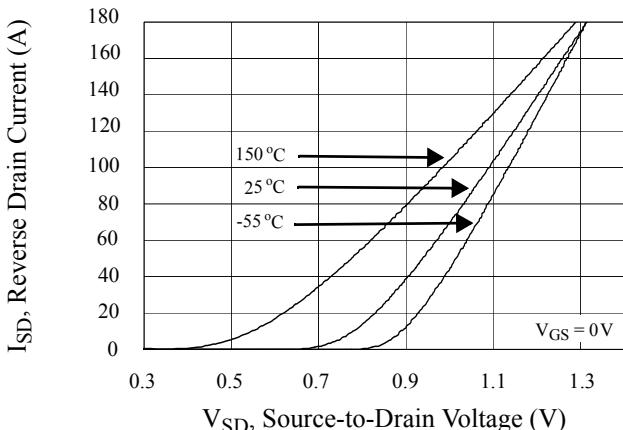
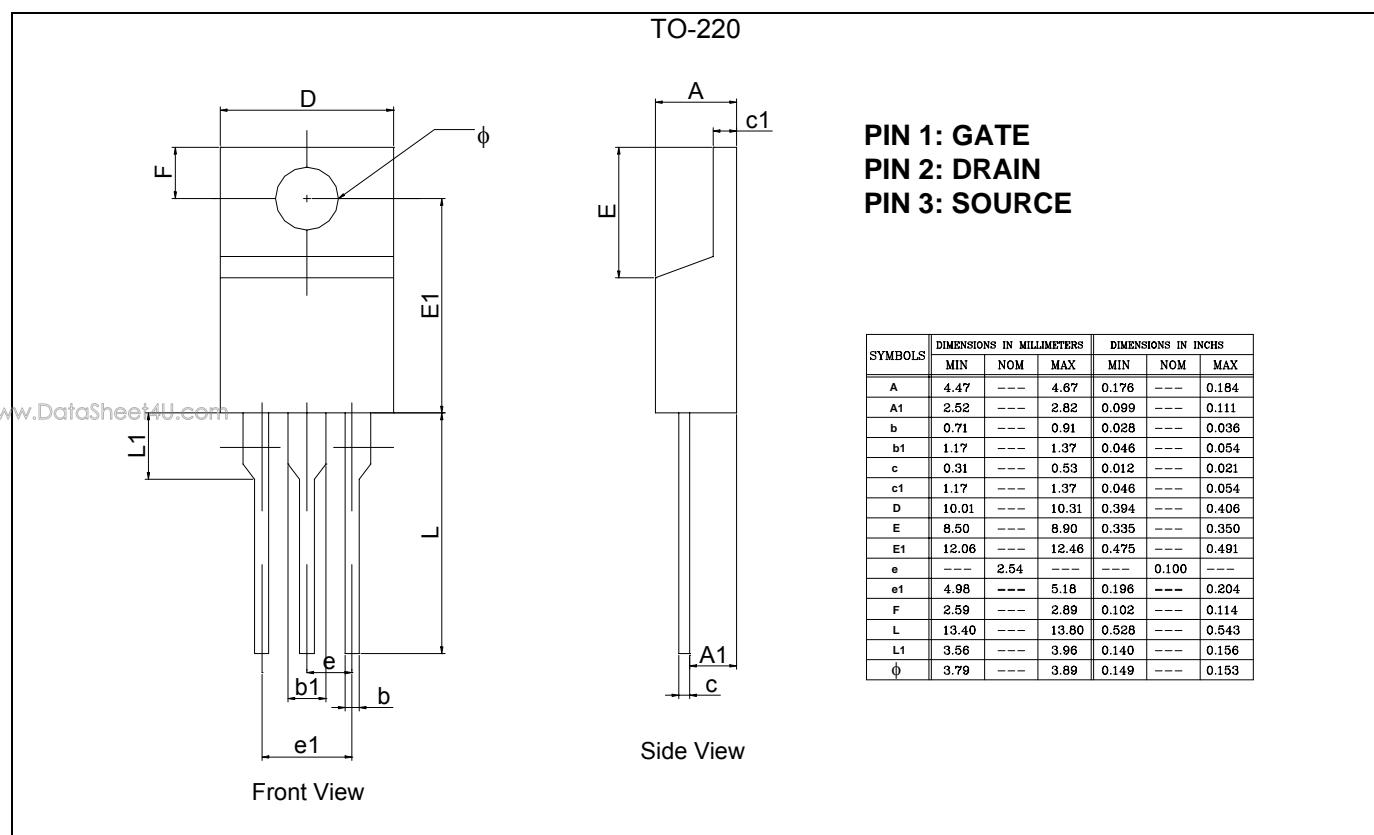
I<sub>SD</sub>, Reverse Drain Current (A)

Figure 16. Typical Body Diode Transfer Characteristics



## PACKAGE DIMENSION





**CMT60N06**

**N-CHANNEL Logic Level Power MOSFET**

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